



SOT398-1

plastic heat-dissipating dual in-line package; 18 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HDIP18
Package type industry code	HDIP18
Package style descriptive code	HDIP (heat-dissipating dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	13-2-2003

Table 1. Package summary

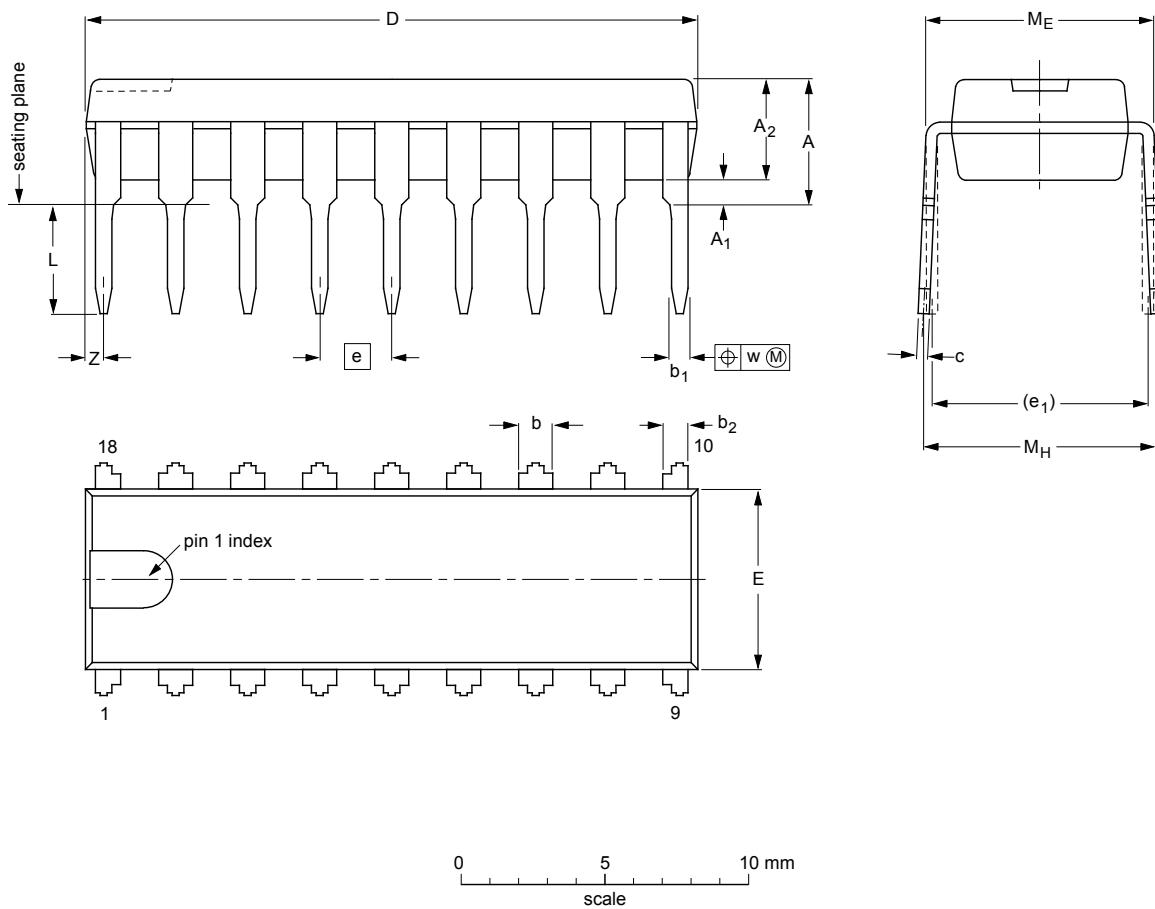
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.35	-	21.6	21.85	mm
E	package width	6.2	-	6.35	6.5	mm
A	seated height	[tbd]	-	4.7	4.7	mm
A ₂	package height	[tbd]	-	3.55	3.7	mm
n ₂	actual quantity of termination	-	-	18	-	



2. Package outline

HDIP18: plastic heat-dissipating dual in-line package; 18 leads

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.67 0.50	1.05 0.75	0.47 0.38	21.85 21.35	6.5 6.2	2.54	7.62	3.9 3.1	8.32 8.02	8.7 7.7	0.25	1
inches	0.19	0.02	0.15	0.06 0.04	0.03 0.02	0.04 0.03	0.02 0.01	0.87 0.84	0.26 0.24	0.1	0.3	0.15 0.12	0.33 0.32	0.34 0.30	0.01	0.04

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT398-1						95-04-25 03-02-13

Fig. 1. Package outline HDIP18 (SOT398-1)

3. Legal information

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